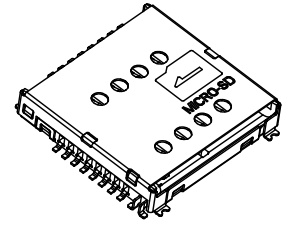
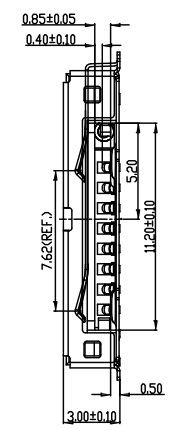
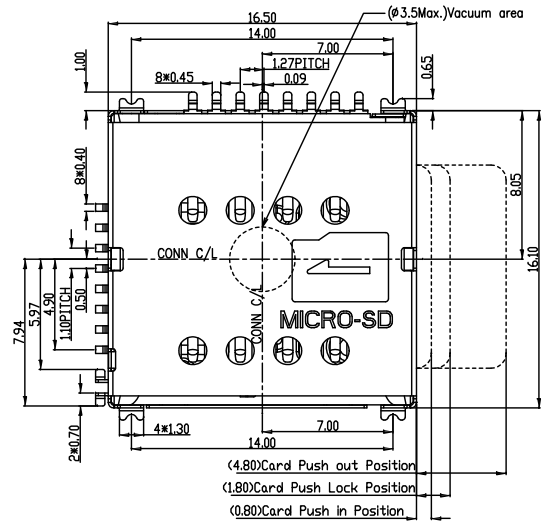
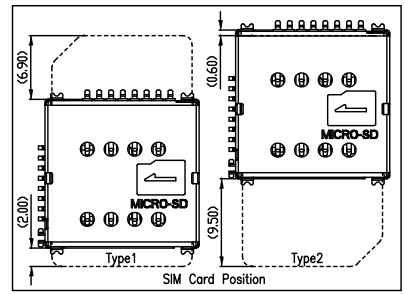
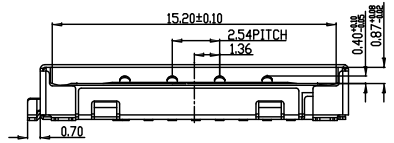


REV.	DESCRIPTION	DATE	DWN	APVD
1	PRELIMINARY	09APR10	JC	BC

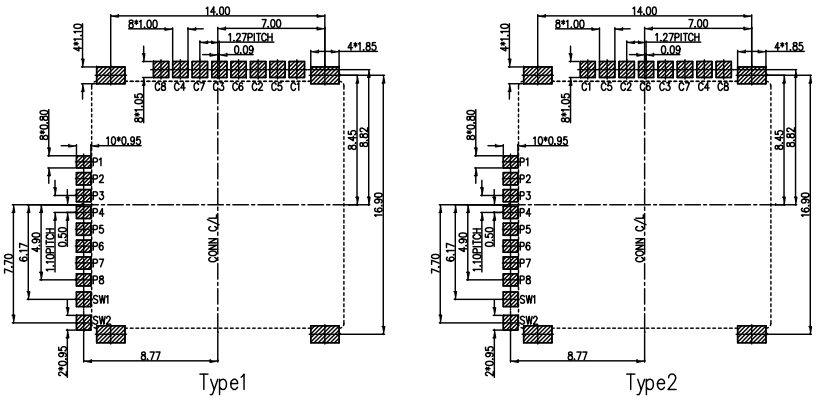


TECHNICAL CHARACTERISTICS

- General Characteristics**
 Dimension: 16.10L x 16.50W x 3.00H mm
 Weight: Approx. 1.02 g
 Contact principle: Friction technology
 Operating position: Shaft up / Down / Horizontal
 Mounting system: SMT Type (without post)
 Micro-SD function: Push-Push Type
 Durability: 5,000 cycles min.
- Mechanical Characteristics**
 Insulation material: Thermoplastic, UL 94V-0
 RoHS Directive 2002/95/EC Compliant
- Electrical Characteristics**
 Number of contacts:
 SIM 8 pins / Micro-SD 8 pins
 Contact resistance: 100mΩ Max.
 Insulation resistance: >1000 MΩ / 500 V DC
 Withstanding voltage: 500 V AC
 Micro SD switch: Blade, Normally Open
- Solderability**
 Wave: Not applicable
 IR reflow: 260°C, 10 sec. Max.
 Manual soldering: 360°C, 3 sec. Max.
- Environmental Characteristics**
 Operating temperature: - 40°C ~ + 85°C
 Operating humidity: 10 % ~ 95 % RH
 Storage temperature: - 40°C ~ + 85°C
 Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: ±0.15 mm
Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm
Reference dimension for PCB layout

J99-0008-01
 PART NUMBER

TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± 0.3 2 PLC ± 0.15 3 PLC ± 0.1 4 PLC ± - ANGLES ± 3°	DWN JOHN_CHANG 09APR2010	HAOGUO XING YE SHARE CO.,LTD.	
	CHK MARKS_CHEN 09APR2010		
MATERIAL SEE NOTE	APVD APVD 09APR2010	SIM+MICRO SD CARD	
FINISH SEE NOTE	PRODUCT SPEC	SIZE A3	DRAWING NO J99-0008
PROJECTION	APPLICATION SPEC	WEIGHT - GRAMS	RESTRICTED TO -
	DIMENSIONS: MM	CUSTOMER DRAWING	SCALE - SHEET 1 OF 1 REV 1